



SOT902-2

plastic, extremely thin quad flat package; 8 terminals; 0.55 mm pitch; 1.6 mm x 1.6 mm x 0.5 mm body

6 February 2017

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN8
Package type industry code	XQFN8
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
IEC package outline code	- - -
JEDEC package outline code	MO-255
JEITA package outline code	- - -
Mounting method type	S (surface mount)
Issue date	12-7-2016
Manufacturer package code	SOT902

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.55	-	1.6	1.65	mm
E	package width	1.55	-	1.6	1.65	mm
A	seated height	-	-	-	0.5	mm
e	nominal pitch	-	-	0.55	-	mm
n ₂	actual quantity of termination	-	-	8	-	

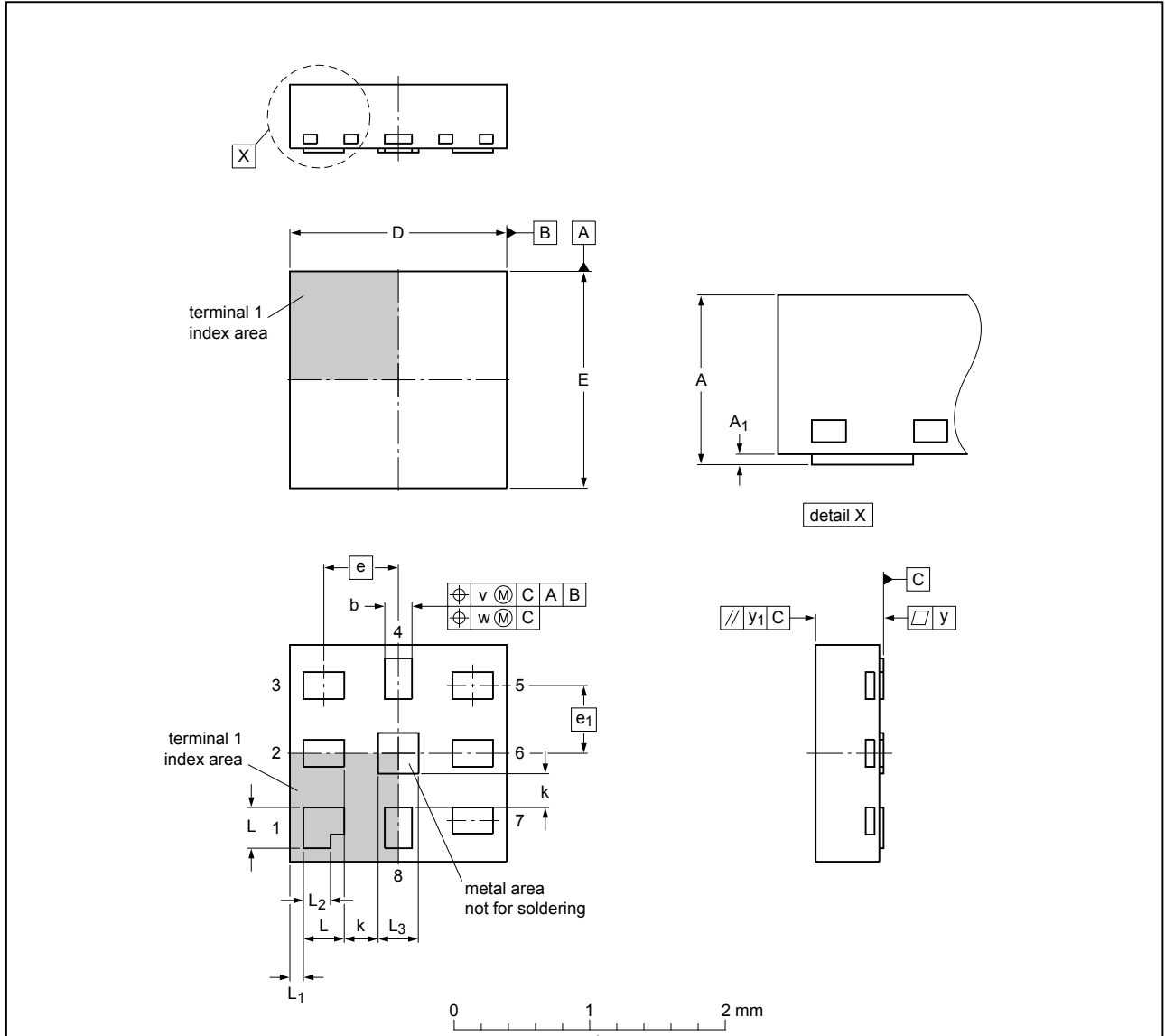


plastic, extremely thin quad flat package; 8 terminals; 0.55 mm pitch; 1.6 mm x 1.6 mm x 0.5 mm body

2. Package outline

**XQFN8: plastic, extremely thin quad flat package; no leads;
8 terminals; body 1.6 x 1.6 x 0.5 mm**

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Dimensions

Unit ⁽¹⁾	A	A ₁	b	D	E	e	e ₁	k	L	L ₁	L ₂	L ₃	v	w	y	y ₁
max	0.5	0.05	0.25	1.65	1.65				0.35	0.15	0.25	0.35				
mm nom			0.20	1.60	1.60	0.55	0.5		0.30	0.10	0.20	0.30	0.1	0.05	0.05	0.05
min		0.00	0.15	1.55	1.55			0.2	0.25	0.05	0.15	0.25				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot902-2_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT902-2	---	MO-255	---		16-07-14 16-11-08

Fig. 1. Package outline XQFN8 (SOT902-2)

plastic, extremely thin quad flat package; 8 terminals; 0.55 mm pitch; 1.6 mm x 1.6 mm x 0.5 mm body

3. Soldering

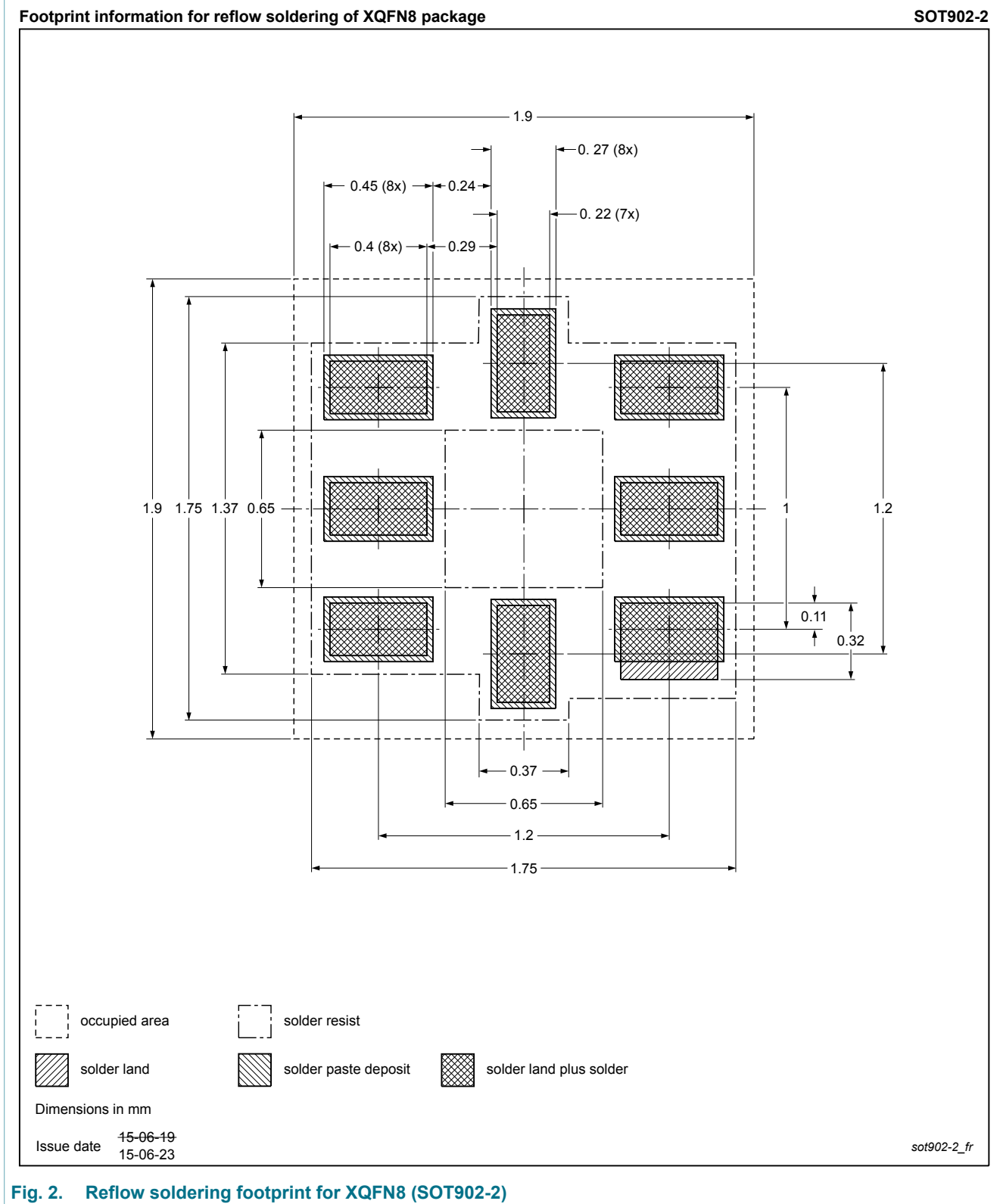


Fig. 2. Reflow soldering footprint for XQFN8 (SOT902-2)

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4. Legal information

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